



18-BIT, 580-kHz, UNIPOLAR INPUT, MICRO POWER SAMPLING ANALOG-TO-DIGITAL CONVERTER WITH PARALLEL INTERFACE

FEATURES

- 580-kHz Sample Rate
- 18-Bit NMC Ensured Over Temperature
- Zero Latency
- Low Power: 115 mW at 580 kHz
- Unipolar Input Range
- Onboard Reference Buffer and Conversion Clock
- Wide Buffer Supply, 2.7 V to 5.25 V
- Flexible 8-/16-/18-Bit Parallel Interface
- Pin Compatible With ADS8383
- 48-Pin TQFP Package

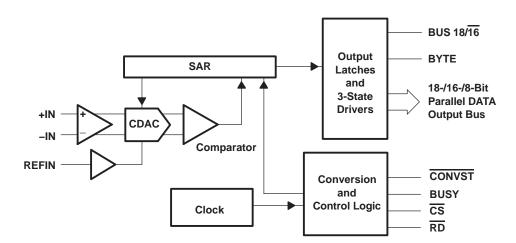
APPLICATIONS

- Medical Instruments
- Optical Networking
- Transducer Interface
- High Accuracy Data Acquisition Systems
- Magnetometers

DESCRIPTION

The ADS8381 is an 18-bit, 580 kHz A/D converter. The device includes a 18-bit capacitor-based SAR A/D converter with inherent sample and hold. The ADS8381 offers a full 18-bit interface, a 16-bit option where data is read using two read cycles, or an 8-bit bus option using three read cycles.

The ADS8381 is available in a 48-lead TQFP package and is characterized over the industrial -40°C to 85°C temperature range.





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.





These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ORDERING INFORMATION

MODEL	MAXIMUM INTEGRAL LINEARITY (LSB)	MAXIMUM DIFFERENTIAL LINEARITY (LSB)	NO MISSING CODES RESOLU- TION (BIT)	PACKAGE TYPE	PACKAGE DESIGNATOR	TEMPER- ATURE RANGE	ORDERING INFORMATION	TRANS- PORT MEDIA QUANTITY
ADC00041		+6 i _2/3 i 17 i i PER i i	−40°C to	ADS8381IPFBT	Tape and reel 250			
ADS8381I	±6		17	TQFP	TQFP	PFB	85°C	ADS8381IPFBR
A D 000041D		4.60	40	48 Pin	550	−40°C to	ADS8381IBPFBT	Tape and reel 250
ADS8381IB	±5	_1/2	18	TQFP	PFB	85°C	ADS8381IBPFBR	Tape and reel 1000

NOTE: For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range unless otherwise noted(1)

			UNIT	
	+IN to AGND		-0.4 V to +VA + 0.1 V	
Voltage	-IN to AGND		-0.4 V to +VA + 0.1 V -0.4 V to 0.5 V -0.3 V to 7 V -0.3 V to 7 V -0.3 V to 2.55 V -0.3 V to +VBD + 0.3 V -0.3 V to +VBD + 0.3 V -40°C to 85°C -65°C to 150°C 150°C (TJMax - TA)/θJA 86°C/W 215°C	
	+VA to AGND		−0.3 V to 7 V	
Voltage range	+VBD to BDGND		−0.3 V to 7 V	
	+VA to +VBD		−0.3 V to 2.55 V	
Digital input voltage	to BDGND	-0.3 V to +VBD + 0.3 V		
Digital output voltage	ge to BDGND	-0.3 V to +VBD + 0.3 V		
Operating free-air t	emperature range, T	A	-40°C to 85°C	
Storage temperatur	e range, T _{stg}		−65°C to 150°C	
Junction temperatu	re (T _J max)		150°C	
	Power dissipation		(ТЈМах – ΤΑ)/θЈΑ	
TQFP package	θ _{JA} thermal imped	ance	86°C/W	
		Vapor phase (60 sec)	215°C	
Lead temperature,	soldering	Infrared (15 sec)	220°C	

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



SPECIFICATIONS

 $T_A = -40^{\circ}\text{C}$ to 85°C , +VA = 5 V, +VBD = 3 V or 5 V, $V_{ref} = 4.096$ V, $f_{SAMPLE} = 580$ kHz (unless otherwise noted)

	TEST		ADS8381IE	3	A	DS8381I		
PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
Analog Input				•				
Full-scale input voltage (see Note 1)	+ININ	0		V_{ref}	0		V _{ref}	V
AL	+IN	-0.2		V _{ref} + 0.2	-0.2		V _{ref} + 0.2	.,
Absolute input voltage	-IN	-0.2		0.2	-0.2		0.2	V
Input capacitance			45			45		pF
Input leakage current			1			1		nA
System Performance								
Resolution			18			18		Bits
No missing codes		18			17			Bits
lete and live and control of	< 0.125 FS	-4	-2.2/1	4	-5		5	LSB
Integral linearity (see Notes 2 and 3)	> 0.125 FS	-5	-3/2	5	-6		6	(18 bit)
Differential linearity		-1	-0.6/1.25	2	-2		3	LSB (18 bit)
Offset error		-0.75	±0.25	0.75	-1	±0.5	1	mV
Gain error (see Note 4)		-0.075		0.075	-0.1		0.1	%FS
Noise			60			60		μV RMS
Power supply rejection ratio	At 3FFFFh output code		75			75		dB
Sampling Dynamics				•				
Conversion time				1.4			1.4	μs
Acquisition time		0.3			0.3			μs
Throughput rate				580			580	kHz
Aperture delay			4			4		ns
Aperture jitter			15			15		ps
Step response			150			150		ns
Over voltage recovery			150			150		ns

⁽¹⁾ Ideal input span, does not include gain or offset error.
(2) LSB means least significant bit
(3) This is endpoint INL, not best fit.

⁽⁴⁾ Measured relative to an ideal full-scale input (+IN - -IN) of 4.096 V



SPECIFICATIONS (CONTINUED) TA = -40° C to 85°C, +VA = +5 V, +VBD = 3 V or 5 V, V_{ref} = 4.096 V, f_{SAMPLE} = 580 kHz (unless otherwise noted)

242445	TEST	Al	DS8381IB		Δ	DS8381I		UNIT	
PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
Dynamic Characteristics									
	1 kHz		-112			-110			
T	10 kHz		-106			-100		15	
Total harmonic distortion (THD) (see Note 1)	50 kHz		-98			-95		dB	
	100 kHz		-95			-90			
	1 kHz		88			87			
0: 1: : : : (OND) (N : 1)	10 kHz			87		4D			
Signal to noise ratio (SNR) (see Note 1)	50 kHz		88			87		dB	
	100 kHz		88			87			
	1 kHz				87				
Signal to noise + distortion	10 kHz		88			87		15	
(SINAD) (see Note 1)	50 kHz	50 kHz 87			86			dB	
	100 kHz		87			86			
	1 kHz		113			112			
Spurious free dynamic range (SFDR) (see	10 kHz		108			98		-ID	
Note 1)	50 kHz		99			96		dB	
	100 kHz		97			90			
-3dB Small signal bandwidth			3			3		MHz	
Voltage Reference Input									
Reference voltage at REFIN, V _{ref}		2.5	4.096	4.2	2.5	4.096	4.2	V	
Reference resistance (see Note 2)			500			500		kΩ	
Reference current drain	f _S = 580 kHz			1			1	mA	

⁽¹⁾ Calculated on the first nine harmonics of the input frequency (2) Can vary ±20%



SPECIFICATIONS (CONTINUED) $T_{A} = -40^{\circ}\text{C to }85^{\circ}\text{C, +VA} = +5 \text{ V, +VBD} = 3 \text{ V or 5 V, V}_{\text{ref}} = 4.096 \text{ V, f}_{\text{SAMPLE}} = 580 \text{ kHz (unless otherwise noted)}$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Digital Input/Output		-				
Logic family				CMOS		
	VIH	I _{IH} = 5 μA	+VBD-1		+V _{BD} + 0.3	
Logic level	VIL	I _I L = 5 μA	-0.3		0.8	.,
	VOH	I _{OH} = 2 TTL loads	+V _{BD} - 0.6			V
	VOL	I _{OL} = 2 TTL loads			0.4	
Data format				Straight Binary		
Power Supply Requir	ements					
	+VBD Buffer supply		2.7	3.3	5.25	V
Power Supply Requirements Power supply voltage +VBD Buffer supply +VA Analog supply	+VA Analog supply		4.75	5	5.25	V
Supply current, 580-kh	dz sample rate (see Note 1)			23	26	mA
Power dissipation, 580	ower dissipation, 580-kHz sample rate (see Note 1)			115	130	mW
Temperature Range		<u> </u>				
Operating free-air			-40		85	°C

⁽¹⁾ This includes only +VA current. +VBD current is typical 1 mA with 5 pF load capacitance on all output pins.



TIMING CHARACTERISTICS

All specifications typical at -40 °C to 85 °C, +VA = +VBD = 5 V (see Notes 1, 2, and 3)

	PARAMETER	MIN	TYP	MAX	UNIT
tCONV	Conversion time			1.4	μs
^t ACQ	Acquisition time	0.3			μs
^t HOLD	Sampling capacitor hold time			25	ns
^t pd1	CONVST low to conversion started (BUSY high)			45	ns
tpd2	Propagation delay time, End of conversion to BUSY low			20	ns
t _{pd3}	Propagation delay time, from start of conversion (internal state) to rising edge of BUSY			20	ns
t _{w1}	Pulse duration, CONVST low	40		600	ns
t _{su1}	Setup time, CS low to CONVST low	20			ns
t _{w2}	Pulse duration, CONVST high	20			ns
	CONVST falling edge jitter			10	ps
t _{w3}	Pulse duration, BUSY signal low	Min(t _{ACQ})			μs
t _{w4}	Pulse duration, BUSY signal high			1.4	μs
t _{h1}	Hold time, First data bus data transition (CS low for read cycle, or RD or BYTE or BUS18/16 input changes) after CONVST low	40		600	ns
^t d1	Delay time, CS low to RD low	0			ns
t _{su2}	Setup time, $\overline{\text{RD}}$ high to $\overline{\text{CS}}$ high	0			ns
t _{w5}	Pulse duration, RD low time	50			ns
t _{en}	Enable time, RD low (or CS low for read cycle) to data valid			20	ns
t _{d2}	Delay time, data hold from RD high	5			ns
t _{d3}	Delay time, BUS18/16 or BYTE rising edge or falling edge to data valid	10		20	ns
t _{w6}	Pulse duration, RD high	20			ns
t _{w7}	Pulse duration, CS high time	20			ns
t _{h2}	Hold time, last CS rising edge or changes of RD, BYTE, or BUS18/16 to CONVST falling edge	125			ns
t _{pd4}	Propagation delay time, BUSY falling edge to next RD (or CS for read cycle) falling edge	Max(t _{d5})			ns
t _{d4}	Delay time, BYTE edge to BUS18/16 edge skew	0			ns
t _{su3}	Setup time, BYTE or BUS18/16 transition to RD falling edge	10			ns
t _{h3}	Hold time, BYTE or BUS18/16 transition to RD falling edge	10			ns
^t dis	Disable time, RD High (CS high for read cycle) to 3-stated data bus			20	ns
t _{d5}	Delay time, BUSY low to MSB data valid			30	ns
t _{su5}	Setup time, BYTE transition to next BYTE transition, or BUS18/16 transition to next BUS18/16 transition	50			ns
^t su(AB)	Setup time, from the falling edge of $\overline{\text{CONVST}}$ (used to start the valid conversion) to the next falling edge of $\overline{\text{CONVST}}$ (when $\overline{\text{CS}} = 0$ and $\overline{\text{CONVST}}$ used to abort) or to the next falling edge of $\overline{\text{CS}}$ (when $\overline{\text{CS}}$ is used to abort).	65		1000	ns
t _f (CONVST)	Falling time, (CONVST falling edge)	10		30	ns
t _{su6}	Setup time, \overline{CS} falling edge to \overline{CONVST} falling edge when $\overline{RD} = 0$	125			ns

⁽¹⁾ All input signals are specified with t_r = t_f = 5 ns (10% to 90% of +VBD) and timed from a voltage level of (V_{IL} + V_{IH})/2 except for CONVST.
(2) See timing diagrams.
(3) All timing are measured with 20 pF equivalent loads on all data bits and BUSY pins.



TIMING CHARACTERISTICS

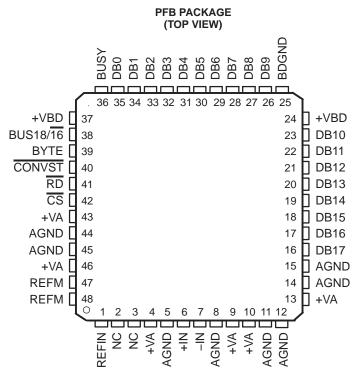
All specifications typical at -40° C to 85° C, +VA = 5 V, +VBD = 3 V (see Notes 1, 2, and 3)

	PARAMETER	MIN	TYP	MAX	UNIT
tCONV	Conversion time			1.4	μs
tACQ	Acquisition time	0.3			μs
tHOLD	Sampling capacitor hold time			25	ns
^t pd1	CONVST low to conversion started (BUSY high)			50	ns
t _{pd2}	Propagation delay time, end of conversion to BUSY low			25	ns
tpd3	Propagation delay time, from start of conversion (internal state) to rising edge of BUSY			25	ns
t _{w1}	Pulse duration, CONVST low	40		600	ns
tsu1	Setup time, CS low to CONVST low	20			ns
t _{w2}	Pulse duration, CONVST high	20			ns
	CONVST falling edge jitter			10	ps
t _{w3}	Pulse duration, BUSY signal low	Min(t _{ACQ})			μs
t _{W4}	Pulse duration, BUSY signal high			1.4	μs
^t h1	Hold time, first data bus transition (CS low for read cycle, or RD or BYTE or BUS 18/16 input changes) after CONVST low	40		600	ns
^t d1	Delay time, CS low to RD low	0			ns
t _{su2}	Setup time, RD high to CS high	0			ns
t _{w5}	Pulse duration, RD low	50			ns
t _{en}	Enable time, RD low (or CS low for read cycle) to data valid			30	ns
t _{d2}	Delay time, data hold from RD high	10			ns
t _{d3}	Delay time, BUS18/16 or BYTE rising edge or falling edge to data valid	10		30	ns
t _{w6}	Pulse duration, RD high time	20			ns
t _{w7}	Pulse duration, CS high time	20			ns
t _{h2}	Hold time, last CS rising edge or changes of RD, BYTE, or BUS18/16 to CONVST falling edge	125			ns
^t pd4	Propagation delay time, BUSY falling edge to next RD (or CS for read cycle) falling edge	Max(td5)			ns
t _{d4}	Delay time, BYTE edge to BUS18/16 edge skew	0			ns
t _{su3}	Setup time, BYTE or BUS18/16 transition to RD falling edge	10			ns
t _{h3}	Hold time, BYTE or BUS18/16 transition to RD falling edge	10			ns
^t dis	Disable time, RD High (CS high for read cycle) to 3-stated data bus			30	ns
t _{d5}	Delay time, BUSY low to MSB data valid delay time			40	ns
t _{su5}	Setup time, BYTE transition to next BYTE transition, or BUS18/16 transition to next BUS18/16 transition	50			ns
^t su(AB)	Setup time, from the falling edge of $\overline{\text{CONVST}}$ (used to start the valid conversion) to the next falling edge of $\overline{\text{CONVST}}$ (when $\overline{\text{CS}} = 0$ and $\overline{\text{CONVST}}$ used to abort) or to the next falling edge of $\overline{\text{CS}}$ (when $\overline{\text{CS}}$ is used to abort).	70		1000	ns
t _f (CONVST)	Falling time, (CONVST falling edge)	10		30	ns
t _{su6}	Setup time, \overline{CS} falling edge to \overline{CONVST} falling edge when $\overline{RD} = 0$	125			ns

⁽¹⁾ All input signals are specified with t_r = t_f = 5 ns (10% to 90% of +VBD) and timed from a voltage level of (V_{IL} + V_{IH})/2 except for CONVST.
(2) See timing diagrams.
(3) All timing are measured with 10 pF equivalent loads on all data bits and BUSY pins.



PIN ASSIGNMENTS



NC - No connection.

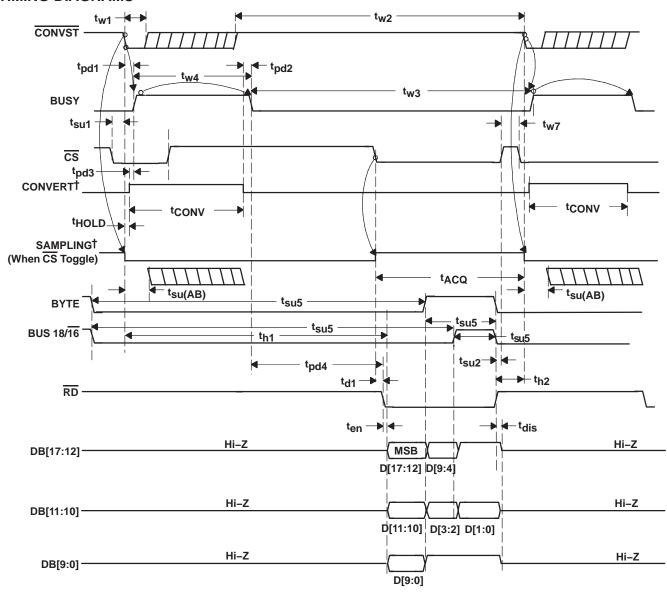


TERMINAL FUNCTIONS

NAME	NO.	I/O			DESCR	RIPTION					
AGND	5, 8, 11,	-	Analog ground								
	12, 14, 15, 44, 45										
BDGND	25	-	Digital ground for	igital ground for buffer supply							
BUSY	36	0	Status output. Hiç	atus output. High when a conversion is in progress.							
BUS18/16	38	I		•	•	it wide bus transfe	r.				
			1: Last two data bases a) the I	Data bits output on the 18-bit data bus pins DB[17:0]. Last two data bits D[1:0] from 18-bit wide bus output on: a) the low byte pins DB[9:2] if BYTE = 0 b) the high byte pins DB[17:10] if BYTE = 1							
BYTE	39	I	0: No fold back	yte select input. Used for 8-bit bus reading. No fold back Low byte D[9:2] of the 16 most significant bits is folded back to high byte of the 16 most significant pins							
CONVST	40	1		e falling edge of th	is input ends the a	cquisition period ar	nd starts the hold r	period.			
CS	42		-		input starts the ac						
		H		8-Bit Bus			it Bus	18-Bit Bus			
Data Bus			BYTE = 0	BYTE = 1	BYTE = 1	BYTE = 0	BYTE = 0	BYTE = 0			
Data Bus			BUS18/16 = 0	BUS18/16 = 0	BUS18/16 = 1	BUS18/16 = 0	BUS18/16 = 1	BUS18/16 = 0			
DB17	16	0	D17 (MSB)	D9	All ones	D17 (MSB)	All ones	D17 (MSB)			
DB16	17	0	D16	D8	All ones	D16	All ones	D16			
DB15	18	0	D15	D7	All ones	D15	All ones	D15			
DB14	19	0	D14	D6	All ones	D14	All ones	D14			
DB13	20	0	D13								
DB12	21	0	D12	D4	All ones	D12	All ones	D13			
DB11	22	0	D11	D3	D1	D11	All ones	D11			
DB10	23	0	D10	D2	D0(LSB)	D10	All ones	D10			
DB9	26	0	D9	All ones	All ones	D9	All ones	D9			
DB8	27	0	D8	All ones	All ones	D8	All ones	D8			
DB7	28	0	D7	All ones	All ones	D7	All ones	D7			
DB6	29	0	D6	All ones	All ones	D6	All ones	D6			
DB5	30	0	D5	All ones	All ones	D5	All ones	D5			
DB4	31	0	D4	All ones	All ones	D4	All ones	D4			
DB3	32	0	D3	All ones	All ones	D3	D1	D3			
DB2	33	0	D2	All ones	All ones	D2	D0 (LSB)	D2			
DB1	34	0	D1	All ones	All ones	D1	All ones	D1			
DB0	35	0	D0 (LSB)	All ones	All ones	D0 (LSB)	All ones	D0 (LSB)			
-IN	7	ı	Inverting input cha	annel							
+IN	6	I	Noninverting inpu	it channel							
NC	2, 3	-	No connection								
REFIN	1	ı	Reference input.								
REFM	47, 48	I	Reference ground	d.							
RD	41	I		oulse for the parallion result on the b		S is low, this serve	s as the output ena	able and puts the			
+VA	4, 9, 10, 13, 43, 46	-	Analog power sup	oplies, 5-V dc							
+VBD	24, 37	-	Digital power sup	ply for buffer							



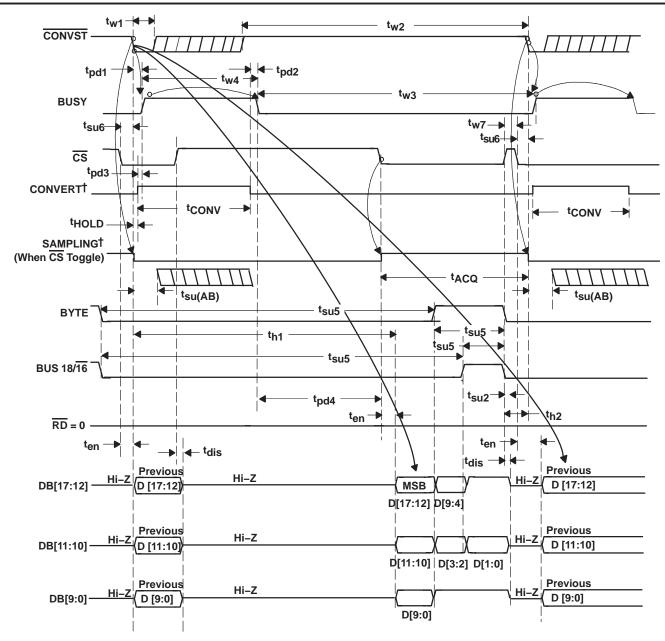
TIMING DIAGRAMS



†Signal internal to device

Figure 1. Timing for Conversion and Acquisition Cycles With $\overline{\text{CS}}$ and $\overline{\text{RD}}$ Toggling

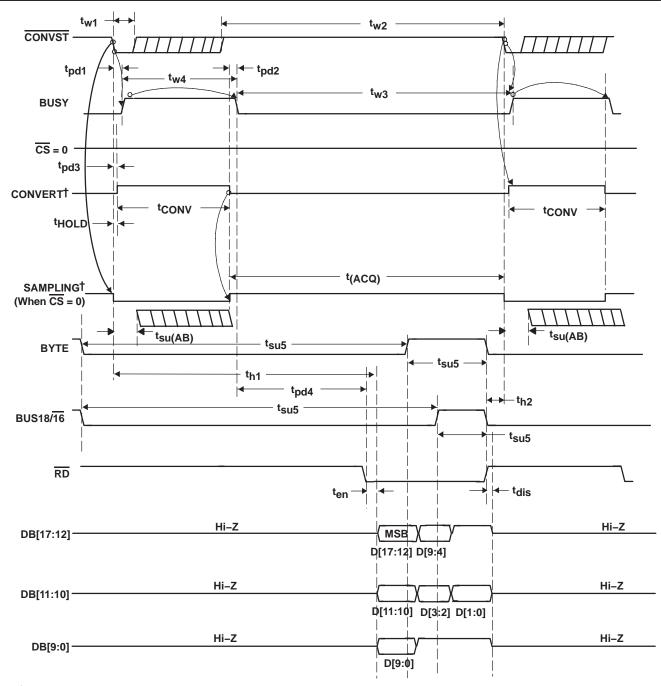




†Signal internal to device

Figure 2. Timing for Conversion and Acquisition Cycles With $\overline{\text{CS}}$ Toggling, $\overline{\text{RD}}$ Tied to BDGND

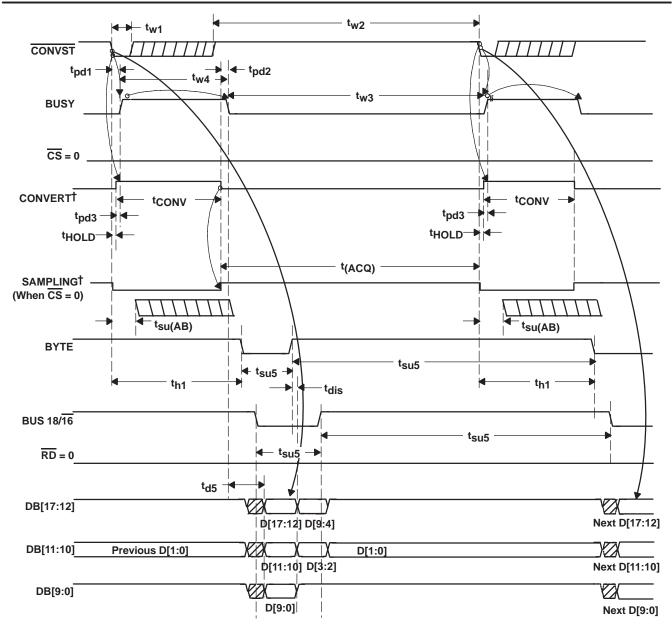




[†]Signal internal to device

Figure 3. Timing for Conversion and Acquisition Cycles With $\overline{\text{CS}}$ Tied to BDGND, $\overline{\text{RD}}$ Toggling





†Signal internal to device

Figure 4. Timing for Conversion and Acquisition Cycles With $\overline{\text{CS}}$ and $\overline{\text{RD}}$ Tied to BDGND—Auto Read



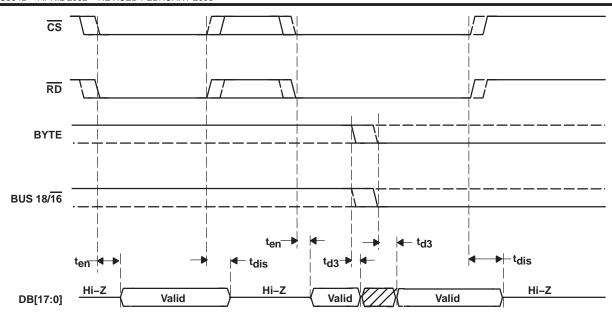


Figure 5. Detailed Timing for Read Cycles



TYPICAL CHARACTERISTICS(1)

HISTOGRAM (DC CODE SPREAD) HALF SCALE 65536 CONVERSIONS

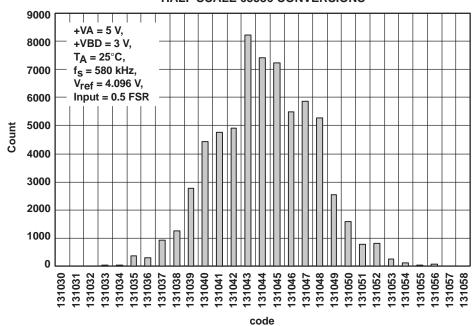
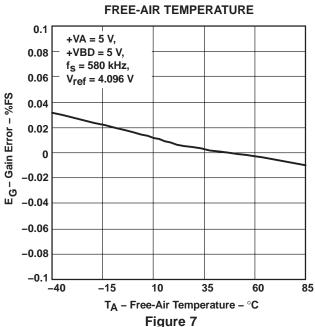


Figure 6



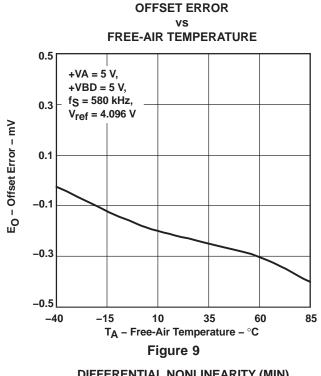


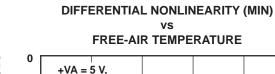
vs FREE-AIR TEMPERATURE 0.1 +VA = 5 V0.08 +VBD = 5 V, $f_S = 580 \text{ kHz},$ 0.06 $V_{ref} = 2.5 V$ E_G - Gain Error - %FS 0.04 0.02 -0.02 -0.04-0.06-0.08 -0.1 -40 10 60 85 T_A – Free-Air Temperature – $^{\circ}C$

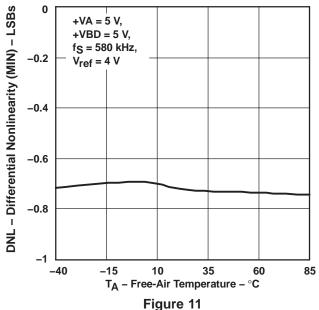
Figure 8

GAIN ERROR









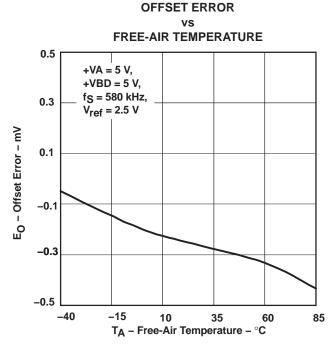
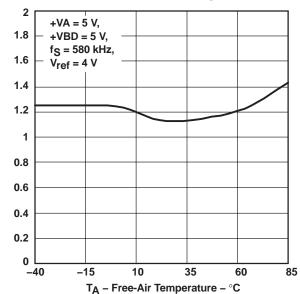


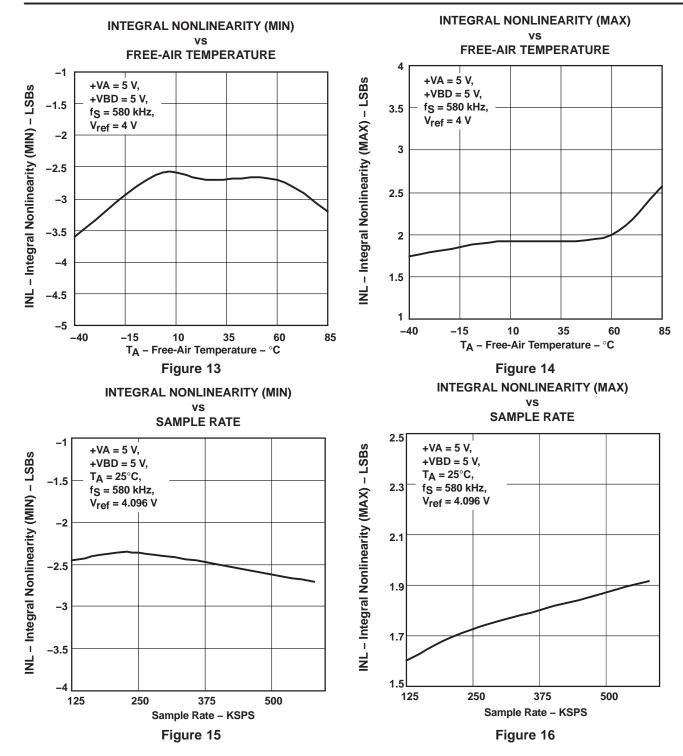
Figure 10
DIFFERENTIAL NONLINEARITY (MAX)
vs
FREE-AIR TEMPERATURE



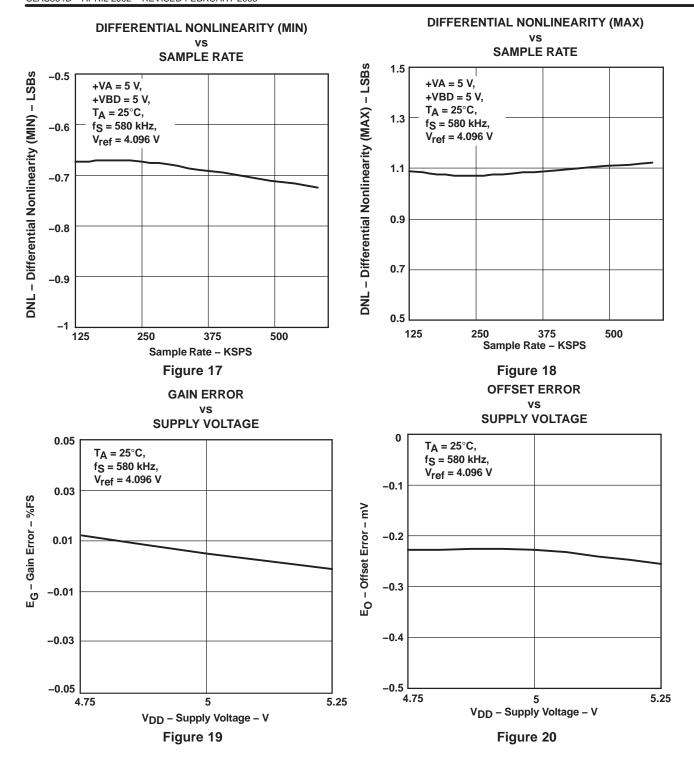
DNL - Differential Nonlinearity (MAX) -LSBs

Figure 12

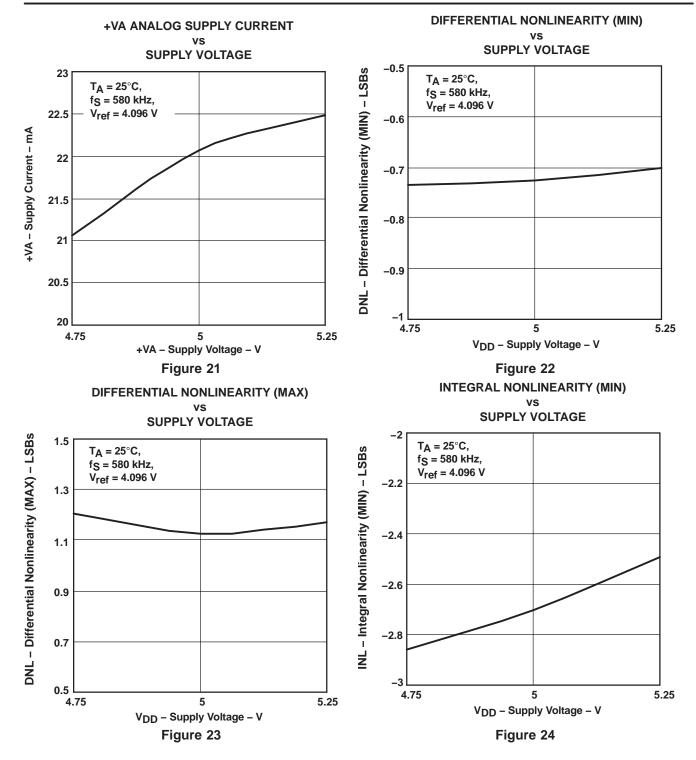




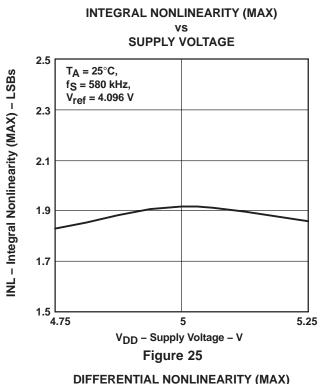




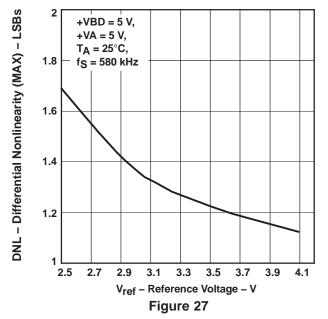








DIFFERENTIAL NONLINEARITY (MAX)
vs
REFERENCE VOLTAGE



DIFFERENTIAL NONLINEARITY (MIN) vs REFERENCE VOLTAGE

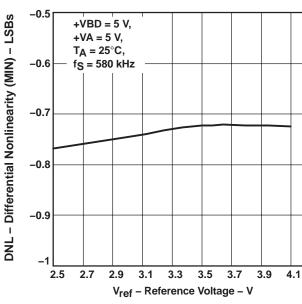


Figure 26
INTEGRAL NONLINEARITY (MIN)
vs

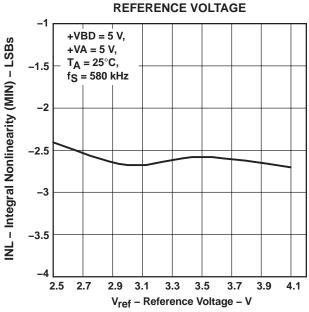
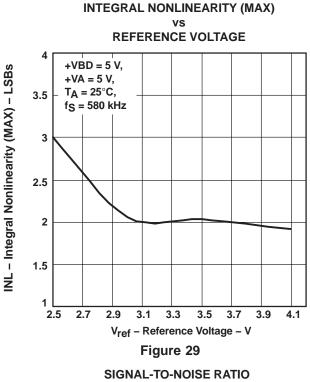
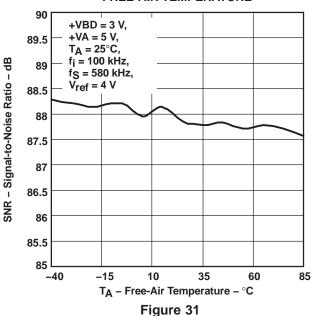


Figure 28









OFFSET ERROR vs REFERENCE VOLTAGE

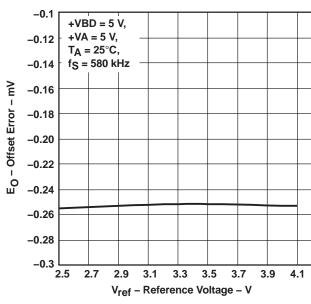


Figure 30
TOTAL HARMONIC DISTORTION
vs

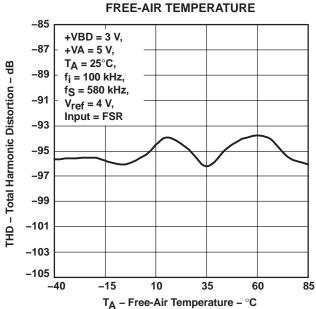
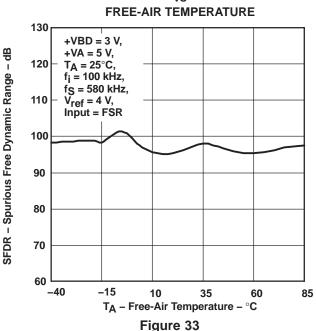


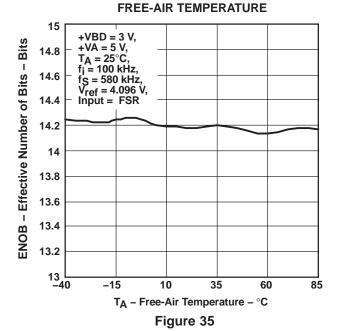
Figure 32



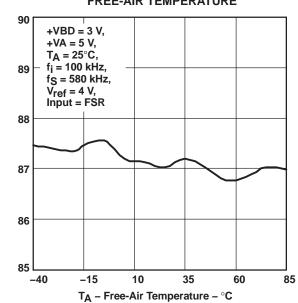
SPURIOUS FREE DYNAMIC RANGE



EFFECTIVE NUMBER OF BITS vs

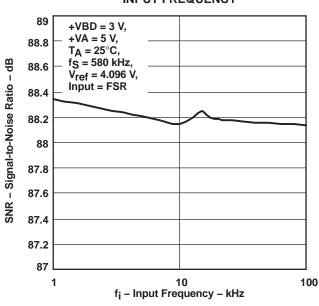


SIGNAL-TO-NOISE AND DISTORTION vs FREE-AIR TEMPERATURE

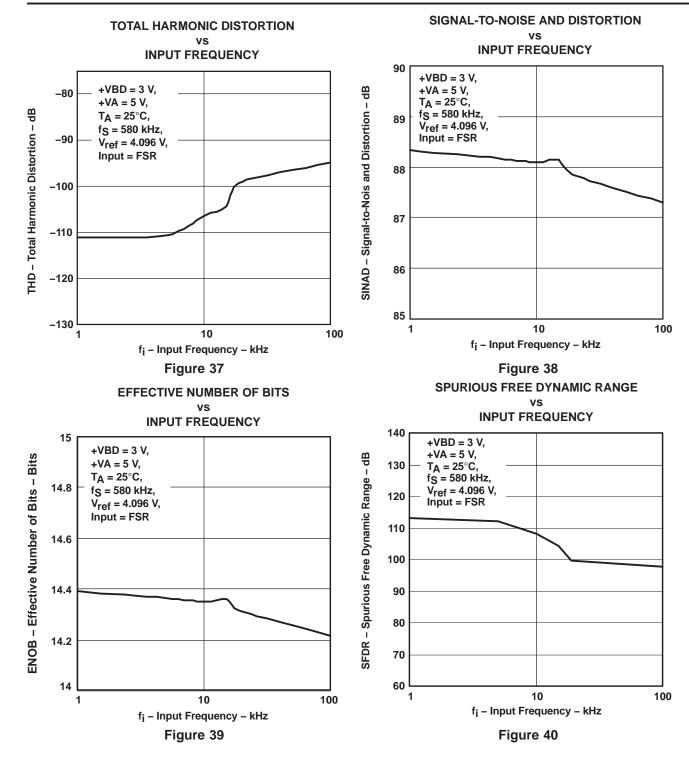


SINAD - Signal-to-Nois and Distortion - dB

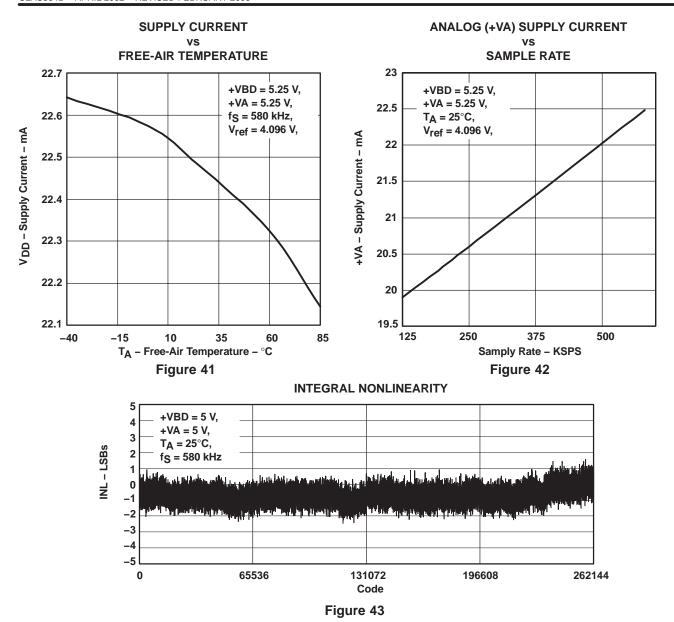
Figure 34
SIGNAL-TO-NOISE RATIO
vs
INPUT FREQUENCY















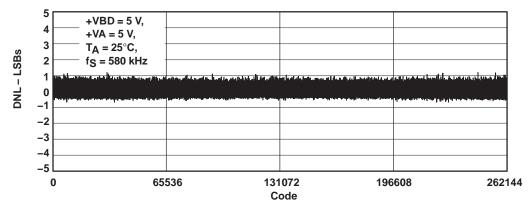


Figure 44

FFT

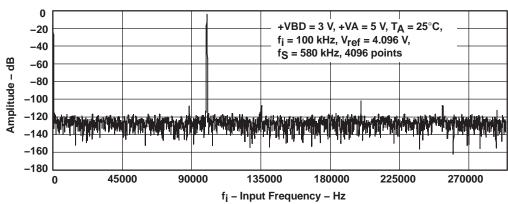


Figure 45



APPLICATION INFORMATION

MICROCONTROLLER INTERFACING

ADS8381 to 8-Bit Microcontroller Interface

Figure 46 shows a parallel interface between the ADS8381 and a typical microcontroller using the 8-bit data bus. The BUSY signal is used as a falling-edge interrupt to the microcontroller.

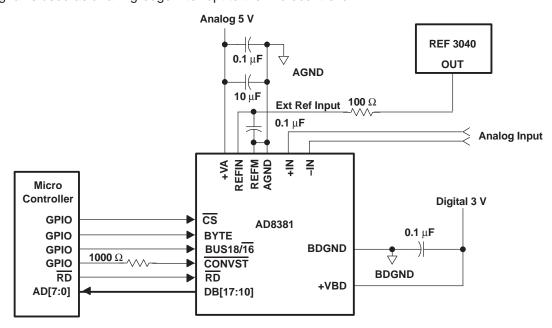


Figure 46. ADS8381 Application Circuitry



PRINCIPLES OF OPERATION

The ADS8381 is a high-speed successive approximation register (SAR) analog-to-digital converter (ADC). The architecture is based on charge redistribution which inherently includes a sample/hold function. See Figure 46 for the application circuit for the ADS8381.

The conversion clock is generated internally. The conversion time of 1.4 μs is capable of sustaining a 580-kHz throughput.

The analog input is provided to two input pins: +IN and -IN. When a conversion is initiated, the differential input on these pins is sampled on the internal capacitor array. While a conversion is in progress, both inputs are disconnected from any internal function.

REFERENCE

The ADS8381 can operate with an external reference with a range from 2.5 V to 4.2 V. The reference voltage on the input pin 1 (REFIN) of the converter is internally buffered. A clean, low noise, well-decoupled reference voltage on this pin is required to ensure good performance of the converter. A low noise band-gap reference like the REF3040 can be used to drive this pin. A 0.1-uF decoupling capacitor is required between pin 1 and pin 48 of the converter. This capacitor should be placed as close as possible to the pins of the device. Designers should strive to minimize the routing length of the traces that connect the terminals of the capacitor to the pins of the converter. An RC network can also be used to filter the reference voltage. A $100-\Omega$ series resistor and a 0.1-uF capacitor, which can also serve as the decoupling capacitor, can be used to filter the reference voltage.

ANALOG INPUT

When the converter enters the hold mode, the voltage difference between the +IN and –IN inputs is captured on the internal capacitor array. The voltage on the –IN input is limited between –0.2 V and 0.2 V, allowing the input to reject small signals which are common to both the +IN and –IN inputs. The +IN input has a range of –0.2 V to V_{ref} + 0.2 V. The input span (+IN – (–IN)) is limited to 0 V to V_{ref} .

The input current on the analog inputs depends upon a number of factors: sample rate, input voltage, and source impedance. Essentially, the current into the ADS8381 charges the internal capacitor array during the sample period. After this capacitance has been fully charged, there is no further input current. The source of the analog input voltage must be able to charge the input capacitance (45 pF) to an 18-bit settling level within the acquisition time (300 ns) of the device. When the converter goes into the hold mode, the input impedance is greater than 1 $G\Omega$.

Care must be taken regarding the absolute analog input voltage. To maintain the linearity of the converter, the +IN and -IN inputs and the span (+IN - (-IN)) should be within the limits specified. Outside of these ranges, the converter's linearity may not meet specifications. To minimize noise, low bandwidth input signals with low-pass filters should be used.

Care should be taken to ensure that the output impedance of the sources driving the +IN and -IN inputs are matched. If this is not observed, the two inputs could have different setting times. This may result in offset error, gain error, and linearity error which changes with temperature and input voltage.

The analog input to the converter needs to be driven with a low noise, high-speed op-amp like the THS4031. An RC filter is recommended at the input pins to low-pass filter the noise from the source. A series resistor of 15 Ω and a decoupling capacitor of 1.2 nF is recommended.

The input to the converter is a unipolar input voltage in the range 0 V to V_{ref}. The THS4031 can be used in the source follower configuration to drive the converter.



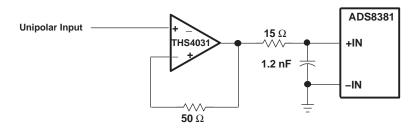


Figure 47. Unipolar Input to Converter

In systems where the input is bipolar, the THS4031 can be used in the inverting configuration with an additional DC bias applied to its + input so as to keep the input to the ADS8381 within its rated operating voltage range. This configuration is also recommended when the ADS8381 is used in signal processing applications where good SNR and THD performance is required. The DC bias can be derived from the REF3020 or the REF3040 reference voltage ICs. The input configuration shown below is capable of delivering better than 88-dB SNR and –95-db THD at an input frequency of 100 kHz. In case bandpass filters are used to filter the input, care should be taken to ensure that the signal swing at the input of the bandpass filter is small so as to keep the distortion introduced by the filter minimal. In such cases, the gain of the circuit shown in Figure 48 can be increased to keep the input to the ADS8381 large to keep the SNR of the system high. Note that the gain of the system from the + input to the output of the THS4031 in such a configuration is a function of the gain of the AC signal. A resistor divider can be used to scale the output of the REF3020 or REF3040 to reduce the voltage at the DC input to THS4031 to keep the voltage at the input of the converter within its rated operating range.

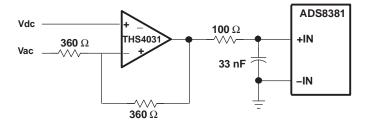


Figure 48. Bipolar Input to Converter

DIGITAL INTERFACE

Timing And Control

See the timing diagrams in the specifications section for detailed information on timing signals and their requirements.

The ADS8381 uses an internal oscillator generated clock which controls the conversion rate and in turn the throughput of the converter. No external clock input is required.

Conversions are initiated by bringing the $\overline{\text{CONVST}}$ pin low for a minimum of 40 ns (after the 40 ns minimum requirement has been met, the $\overline{\text{CONVST}}$ pin can be brought high), while $\overline{\text{CS}}$ is low. The BUSY output is brought high immediately following $\overline{\text{CONVST}}$ going low. BUSY stays high throughout the conversion process and returns low when the conversion has ended. Sampling starts with the falling edge of the BUSY signal when $\overline{\text{CS}}$ is tied low or starts with the falling edge of $\overline{\text{CS}}$ when BUSY is low.

Both \overline{RD} and \overline{CS} can be high during and before a conversion with one exception (\overline{CS} must be low when \overline{CONVST} goes low to initiate a conversion). Both the \overline{RD} and \overline{CS} pins are brought low in order to enable the parallel output bus with the conversion.



Digital Inputs

The converter switches from sample to hold mode at the falling edge of the $\overline{\text{CONVST}}$ input pin. A clean and low jitter falling edge is important to the performance of the converter. A sharp falling transition on this pin can affect the voltage that is acquired by the converter. A falling transition time in the range of 10 ns to 30 ns is required to achieve the rated performance of the converter. A resistor of approximately 1000 Ω (10% tolerance) can be placed in series with the $\overline{\text{CONVST}}$ input pin to satisfy this requirement.

The other digital inputs to the ADS8381 do not require any resistors in series with them. However, certain precautions are necessary to ensure that transitions on these inputs do not affect converter performance. It is recommended that all activity on the input pins happen during the first 600 ns of the conversion period. This allows the error correction circuits inside the device to correct for any errors that these activities cause on the converter output. For example, when the converter is operated with $\overline{\text{CS}}$ and $\overline{\text{RD}}$ tied to ground, the signal $\overline{\text{CONVST}}$ can be brought low to initiate a conversion and brought high after a duration not exceeding 600 ns. Figure 49 shows the recommended timing for the $\overline{\text{CONVST}}$ input with $\overline{\text{RD}}$ and $\overline{\text{CS}}$ tied low.

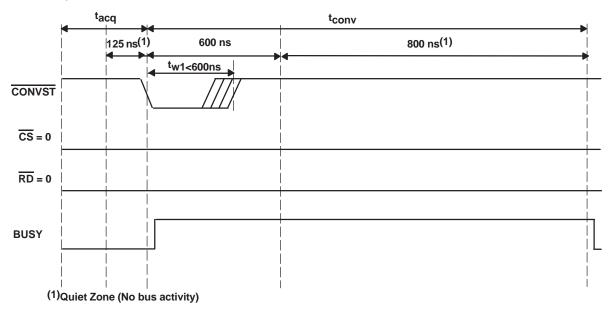


Figure 49. Timing for \overline{CONVST} When $\overline{CS} = \overline{RD} = \overline{BDGND}$



A similar precaution applies when \overline{RD} is used to three-state the output buffers after a data-read operation. A minimum quite period of 125 ns is also required from the instant the data is changed on the bus (such as the falling or rising edge of \overline{RD} , the falling or rising edge of BYTE, and the falling or rising edge of BUS18/ $\overline{16}$) is made available on the data bus pins to the sampling instant (falling edge of \overline{CONVST}). Figure 50 shows the timing of the input control signals that allow these conditions to be satisfied.

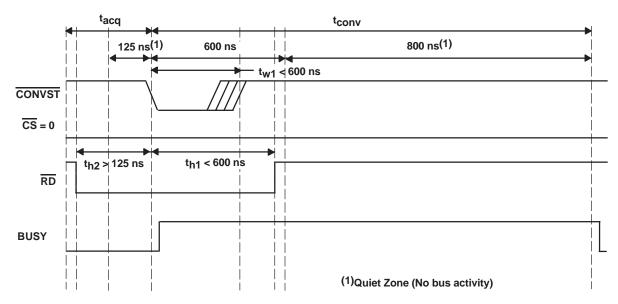


Figure 50. Bus Activity Split to Avoid Quiet Zone

If the \overline{RD} pin is brought high to three-state the data buses, the three-stating operation should occur 125 ns before the end of the acquisition phase. Figure 51 shows the recommended timing for using the ADS8381 in this mode of operation. The same principle applies to other bus activities such as BYTE and BUS18/ $\overline{16}$.

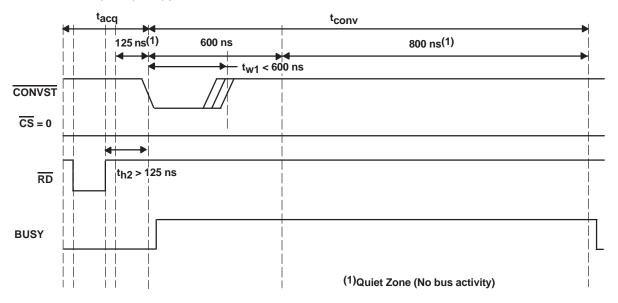


Figure 51. Read Timing if the Bus Needs to be Three-Stated



Reading Data

The ADS8381 outputs full parallel data in straight binary format as shown in Table 1. The parallel output is active when $\overline{\text{CS}}$ and $\overline{\text{RD}}$ are both low. Any other combination of $\overline{\text{CS}}$ and $\overline{\text{RD}}$ sets the parallel output to 3-state. BYTE and BUS18/16 are used for multiword read operations. BYTE is used whenever lower bits on the bus are output on the higher byte of the bus. BUS18/16 is used whenever the last two bits on the 18-bit bus is output on either bytes of the higher 16-bit bus. Refer to Table 1 for ideal output codes.

DESCRIPTION	ANALOG VALUE	DIGITAL OUTPUT			
Full scale range	(+V _{ref})	STRAIGHT BINARY			
Least significant bit (LSB)	(+V _{ref})/262144	BINARY CODE	HEX CODE		
+Full scale	(+V _{ref}) – 1 LSB	11 1111 1111 1111 1111	3FFFF		
Midscale	(+V _{ref})/2	10 0000 0000 0000 0000	20000		
Midscale – 1 LSB	(+V _{ref})/2 - 1 LSB	01 1111 1111 1111 1111	1FFFF		
Zero	0 V	00 0000 0000 0000 0000	00000		

Table 1. Ideal Input Voltages and Output Codes

The output data is a full 18-bit word (D17-D0) on DB17-DB0 pins (MSB-LSB) if both BUS18/16 and BYTE are low.

The result may also be read on an 16-bit bus by using only pins DB17–DB2. In this case two reads are necessary: the first as before, leaving both BUS18/16 and BYTE low and reading the 16 most significant bits (D17–D2) on pins DB17–DB2, then bringing BUS18/16 high while holding BYTE low. When BUS18/16 is high, the lower two bits (D1–D0) appear on pins DB3–DB2.

The result may also be read on an 8-bit bus for convenience. This is done by using only pins DB17–DB10. In this case three reads are necessary: the first as before, leaving both BUS18/16 and BYTE low and reading the 8 most significant bits on pins DB17–DB10, then bringing BYTE high while holding BUS18/16 low. When BYTE is high, the medium bits (D9–D2) appear on pins DB17–DB10. The last read is done by bringing BUS18/16 high while holding BYTE high. When BUS18/16 is high, the lower two bits (D1–D0) appear on pins DB11–DB10. The last read cycle is not necessary if only the first 16 most significant bits are of interest.

All of these multiword read operations can be performed with multiple active \overline{RD} (toggling) or with \overline{RD} held low for simplicity. This is referred to as the AUTO READ operation.

вуте	DUG40/46	DATA READ OUT					
	BUS18/16	DB17-DB12 PINS	DB11-DB10 PINS	DB9-DB4 PINS	DB3-DB2 PINS	DB1-DB0 PINS	
High	High	All One's	D1-D0	All One's	All One's	All One's	
Low	High	All One's	All One's	All One's	D1-D0	All One's	
High	Low	D9-D4	D3-D2	All One's	All One's	All One's	
Low	Low	D17-D12	D11-D10	D9-D4	D3-D2	D1-D0	

Table 2. Conversion Data Read Out

RESET

The device can be reset through the use of the combination fo \overline{CS} and \overline{CONVST} . Since the BUSY signal is held at high during the conversion, either one of these conditions triggers an internal self-clear reset to the converter.

- Issue a CONVST when CS is low and internal CONVERT state is high. The falling edge of CONVST starts a reset.
- Issue a $\overline{\text{CS}}$ (select the device) while internal CONVERT state is high. The falling edge of $\overline{\text{CS}}$ causes a reset.

Once the device is reset, all output latches are cleared (set to zeroes) and the BUSY signal is brought low. A new sampling period is started at the falling edge of the BUSY signal immediately after the instant of the internal reset.



INITIALIZATION

At first power on there are three read cycles required (\overline{RD} must be toggled three times). If conversion cycle is attempted before these initialization read cycles, the first three conversion cycles will not produce valid results. This is used to load factory trimming data for a specific device to assure high accuracy of the converter. Because of this requirement, the \overline{RD} pin cannot be tied permanently to BDGND. System designers can still achieve the AUTO READ function if the power-on requirement is satisfied.

LAYOUT

For optimum performance, care should be taken with the physical layout of the ADS8381 circuitry.

As the ADS8381 offers single-supply operation, it will often be used in close proximity with digital logic, microcontrollers, microprocessors, and digital signal processors. The more digital logic present in the design and the higher the switching speed, the more difficult it is to achieve good performance from the converter.

The basic SAR architecture is sensitive to glitches or sudden changes on the power supply, reference, ground connections and digital inputs that occur just prior to latching the output of the analog comparator. Thus, driving any single conversion for an n-bit SAR converter, there are at least n *windows* in which large external transient voltages can affect the conversion result. Such glitches might originate from switching power supplies, nearby digital logic, or high power devices.

The degree of error in the digital output depends on the reference voltage, layout, and the exact timing of the external event.

On average, the ADS8381 draws very little current from an external reference as the reference voltage is internally buffered. If the reference voltage is external and originates from an op amp, make sure that it can drive the bypass capacitor or capacitors without oscillation. A 0.1-µF bypass capacitor is recommended from pin 1 (REFIN) directly to pin 48 (REFM). REFM and AGND should be shorted on the same ground plane under the device.

The AGND and BDGND pins should be connected to a clean ground point. In all cases, this should be the analog ground. Avoid connections which are too close to the grounding point of a microcontroller or digital signal processor. If required, run a ground trace directly from the converter to the power supply entry point. The ideal layout consists of an analog ground plane dedicated to the converter and associated analog circuitry.

As with the AGND connections, +VA should be connected to a 5-V power supply plane or trace that is separate from the connection for digital logic until they are connected at the power entry point. Power to the ADS8381 should be clean and well bypassed. A 0.1- μ F ceramic bypass capacitor should be placed as close to the device as possible. See Table 3 for the placement of the capacitor. In addition, a 1- μ F to 10- μ F capacitor is recommended. In some situations, additional bypassing may be required, such as a 100- μ F electrolytic capacitor or even a Pi filter made up of inductors and capacitors—all designed to essentially low-pass filter the 5-V supply, removing the high frequency noise.

Table 3. Power Supply Decoupling Capacitor Placement

POWER SUPPLY PLANE	CONVERTED ANALOGOUS	CONVERTED DIGITAL CIDE	
SUPPLY PINS	CONVERTER ANALOG SIDE	CONVERTER DIGITAL SIDE	
Pin pairs that require shortest path to decoupling capacitors	(4,5), (8,9), (10,11), (13,15), (43,44), (45,46)	(24,25)	
Pins that require no decoupling	12, 14	37	

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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
ADS8381IBPFBT	Active	Production	TQFP (PFB) 48	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	ADS8381I B
ADS8381IBPFBT.B	Active	Production	TQFP (PFB) 48	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	ADS8381I B

⁽¹⁾ Status: For more details on status, see our product life cycle.

- (4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.



PLASTIC QUAD FLATPACK



NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 This drawing is subject to change without notice.
 Reference JEDEC registration MS-026.



PLASTIC QUAD FLATPACK



NOTES: (continued)

- 4. Publication IPC-7351 may have alternate designs.
- 5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



PLASTIC QUAD FLATPACK



NOTES: (continued)



^{6.} Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

^{7.} Board assembly site may have different recommendations for stencil design.

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